

Application Serial No. 10/649,577
Attorney Docket No.: 0140153

In the Claims:

Claim 1 (currently amended): A method for forming a package for an ~~electrical~~ electronic device, said method comprising the steps of:

attaching a removable material to a surface of a conductive material, wherein said removable material comprises a soluble adhesive;

forming isolated conductive features within said conductive material;

forming a die attach pad within said conductive material;

coupling said electronic device to said die attach pad;

attaching an encapsulant to said isolated conductive features, said die attach pad, said electronic device, and said removable material; and

removing said removable material from said conductive features, said die attach pad, and said encapsulant by dissolving said soluble adhesive, thereby forming said package for said electronic device.

Claim 2 (original): The method for forming a package for the electronic device of claim 1, wherein said forming step includes patterning a surface of said conductive material with a material resistant to an etchant and etching said conductive material with said etchant.

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Claims 3-4 (cancelled).

Claim 5 (original): The method for forming a package for an electronic device of claim 1, further comprising the step of electrically coupling an input/output portion of the device to said isolated conductive feature.

Claim 6 (original): The method for forming a package for the electronic device of claim 1, further comprising the step of singulating individual packaged devices.

Claim 7 (original): The method of claim 1, wherein the removable material is water soluble adhesive.

Claim 8 (original): The method of claim 7, wherein the removable material is removed with deionized water.

Claims 9-15 (cancelled).

Claim 16 (previously presented): The method of claim 1, wherein the removable material is mold stencil that is used in said attaching encapsulant step.

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Claim 17 (previously presented): The method of claim 1, wherein the removable material comprises a polyimide material and a water soluble adhesive.

Claims 18-19 (cancelled).

Claim 20 (previously presented): The method of claim 1, wherein said conductive material comprises a metal frame.

Claim 21 (previously presented): The method of claim 20, wherein the metal frame comprises a leadframe.

Claim 22 (currently amended): The method of claim 21, ~~further comprising the step of forming a die attach pad within said conductive materials, wherein said die attach pad is not offset from said isolated conductive features.~~

Claim 23 (previously presented): The method of claim 21, wherein a single row of connectors is formed around a perimeter of said leadframe.

Claim 24 (previously presented): The method of claim 20, wherein said metal frame comprises a metal sheet.

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Claim 25 (previously presented): The method of claim 24, wherein multiple rows of connectors are formed around a perimeter of the metal sheet.

Claim 26 (previously presented): The method of claim 20, wherein the removable material covers substantially the entire bottom surface of said metal frame.

Claim 27 (currently amended): The method of claim [[4]] 1, wherein the electronic device is coupled to said die attach pad via conductive epoxy.

Claim 28 (currently amended): A method for forming a package for an ~~electrical~~ electronic device, said method comprising the steps of:

attaching a removable material to a surface of a conductive material before one or more isolated conductive features have been formed within said conductive material, wherein said removable material comprises a soluble adhesive;

forming said isolated conductive features within said conductive material;

forming a die attach pad within said conductive material;

coupling said electronic device to said die attach pad;

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attaching an encapsulant to said isolated conductive features, said die attach pad,
said electronic device, and said removable material, wherein said attaching step is
performed before a singulation process is performed to separate said package; and

removing said removable material from said conductive features, said die attach
pad, and said encapsulant by dissolving said soluble adhesive, thereby forming said
package for said electronic device, wherein the removing said removable material step is
performed after the singulation process is performed to separate said package.